

# Bi<sub>2</sub>Te<sub>3</sub> and Sb<sub>2</sub>Te<sub>3</sub> Thin Films with Enhanced Thermoelectric Properties for Flexible Thermal Sensors <sup>†</sup>

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<sup>†</sup> Presented at the Eurosensors 2018 Conference, Graz, Austria, 9–12 September 2018.

Published: 11 December 2018

**Abstract:** The influence of substrate type in boosting thermoelectric properties of co-evaporated Bi<sub>2</sub>Te<sub>3</sub> and Sb<sub>2</sub>Te<sub>3</sub> films (with 400 nm-thick) is here reported. Optimized power factor values are  $2.7 \times 10^{-3} \text{ W K}^{-2} \text{ m}^{-1}$  and  $1.4 \times 10^{-3} \text{ W K}^{-2} \text{ m}^{-1}$  for flexible Bi<sub>2</sub>Te<sub>3</sub> and Sb<sub>2</sub>Te<sub>3</sub> films, respectively. This is an important result as it is at least 2 times higher than the power factor found in the literature for flexible Bi<sub>2</sub>Te<sub>3</sub> and Sb<sub>2</sub>Te<sub>3</sub> films. A flexible infrared thermopile sensor was developed with high detectivity ( $2.50 \times 10^7 \text{ cm } \sqrt{\text{HzW}^{-1}}$ ).

**Keywords:** telluride alloys; flexible materials; thermoelectricity; IR sensor device

## 1. Introduction

Thermoelectric (TE) technology appears as a green energy source due to their direct transformation of small thermal gradients into electric power, and vice-versa, in a renewable manner and without CO<sub>2</sub> emissions. Telluride alloys have attracted a great deal of interest because of their potential applications as TE generators, TE coolers and thermal sensors [1,2]. The performance of TE devices is highly dependent on TE properties of constituent materials, namely the Seebeck coefficient ( $S$ ), the electrical conductivity ( $\sigma$ ) and the thermal conductivity ( $k$ ), according to the figure of merit ( $ZT$ ),  $ZT = S^2\sigma/k$ , where  $S^2\sigma$  is related to the power factor,  $PF$ . High TE device performance require high  $ZT$  and  $PF$  values. To get high sensitive thermal sensors, TE materials with high  $S$  values are required. Thin films instead of conventional *bulk* materials opens the possibility to reduce substantially the material amount required, and enable the deposition on flexible substrates, making the devices compatible with modern integrated circuit technology.

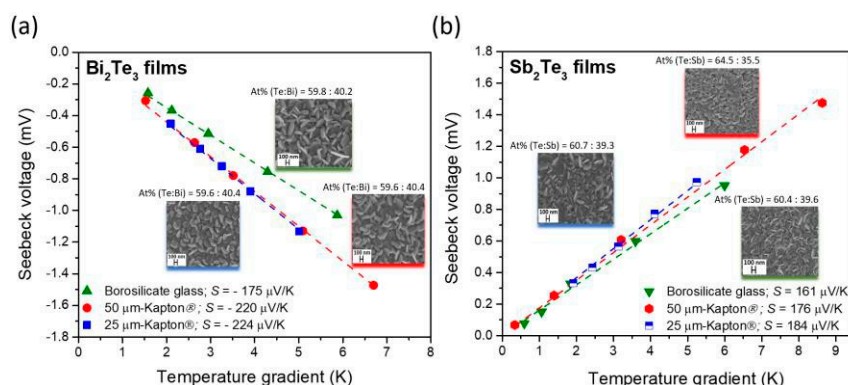
A pioneering work that reports the effect of both substrate thickness and type on the TE properties of Sb<sub>2</sub>Te<sub>3</sub> and Bi<sub>2</sub>Te<sub>3</sub> films, is here discussed. A simple and flexible p-n TE device have been fabricated and tested for pyrometry applications.

## 2. Material and Methods

$\text{Sb}_2\text{Te}_3$  and  $\text{Bi}_2\text{Te}_3$  films (with 400 nm-thick) were fabricated by co-evaporation method in a high-vacuum chamber ( $10^{-6}$  mbar). Bi (or Sb) evaporation rate was  $2 \text{ \AA/s}$  and Te evaporation rate was  $6 \text{ \AA/s}$ . Borosilicate glass and Kapton<sup>®</sup> substrates (with 50- and 25  $\mu\text{m}$ —thick) were used for films deposition. Substrates were heated at 270 °C and 230 °C, for the deposition of  $\text{Sb}_2\text{Te}_3$  and  $\text{Bi}_2\text{Te}_3$  films, respectively. The morphology and chemical composition of the films were obtained by scanning electron microscopy (SEM) and Energy-Dispersive X-ray spectroscopy (EDX). The crystallographic structure was obtained by X-ray diffraction (XRD). In-plane electrical conductivity was measured at room temperature (RT) using the conventional 4-Probe van der Pauw geometry. Seebeck coefficients were obtained by connecting one side of the film to a heated metal block at a fixed temperature and the other side to a heatsink at room temperature, to have a temperature gradient (of a few kelvin) along the film. A flexible thermopile infrared (IR) detector based on the p-n junction ( $5 \times 5 \text{ mm}^2$ ), with a conductive carbon paint as absorber, was developed. The radiation was emitted by a black body target object (15 cm diameter) from 293 K to 513 K of temperature and at a distance of 3 cm. The thermo-voltage generated by the device was monitored by a multimeter.

## 3. Results and Discussion

The thermoelectric voltage generated by the telluride alloys shows a linear dependence of temperature gradient (Figure 1a,b). Maximum  $S$  values of  $-224 \mu\text{V K}^{-1}$  (for  $\text{Sb}_2\text{Te}_3$  film) and  $184 \mu\text{V K}^{-1}$  (for  $\text{Sb}_2\text{Te}_3$  film) deposited on 25  $\mu\text{m}$ —thick Kapton<sup>®</sup> substrates were obtained, respectively. The negative (positive) slope for  $\text{Sb}_2\text{Te}_3$  ( $\text{Bi}_2\text{Te}_3$ ) films is consistent with n-type (p-type) semiconductor behavior. The surface morphology and chemical composition of the films deposited on the three substrates are also shown on Figure 1.



**Figure 1.** Seebeck voltage measured as a function of the induced temperature gradient for (a)  $\text{Bi}_2\text{Te}_3$  and (b)  $\text{Sb}_2\text{Te}_3$  films deposited on the three substrates.  $S$  values calculated from the slope are included. Surface morphology of all films are shown, with corresponding chemical composition of the alloy.

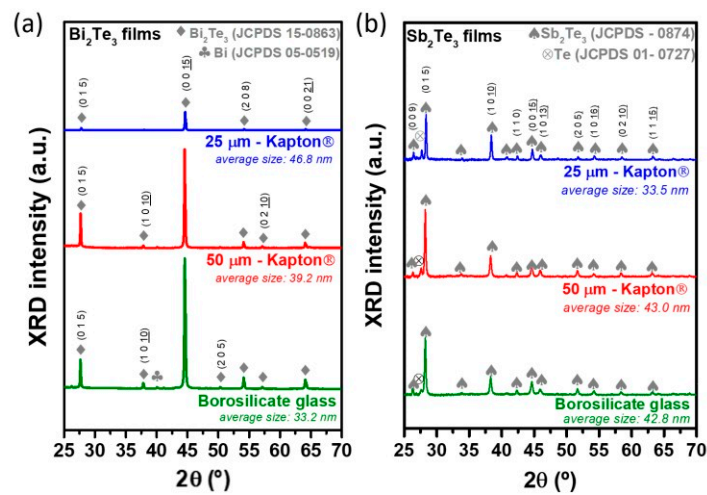
Stoichiometric  $\text{Bi}_2\text{Te}_3$  films ( $\text{At}\%(\text{Te}/\text{Bi}) \approx 1.5$ ) show a dense and grain morphology with large flakes (Figure 1a). However, the film deposited on 25  $\mu\text{m}$ —Kapton<sup>®</sup> shows a more compact structure with more rounded domains.  $\text{Sb}_2\text{Te}_3$  films show a similar surface morphology except for the film deposited on 50  $\mu\text{m}$ —thick Kapton<sup>®</sup> that appears more flat and dense, with smaller crystals. While the films deposited on Kapton<sup>®</sup> substrates are stoichiometric  $\text{Sb}_2\text{Te}_3$ , the film deposited on glass shows a  $\text{At}\%(\text{Te})$  higher than the others films ( $\sim 1.8$ ). Highest  $\sigma$  values are obtained for  $\text{Bi}_2\text{Te}_3$  film deposited on 25  $\mu\text{m}$ —Kapton<sup>®</sup> ( $\approx 5.3 \times 10^4 (\Omega \text{ m})^{-1}$ ) and for the  $\text{Bi}_2\text{Te}_3$  film deposited on 50  $\mu\text{m}$ —Kapton<sup>®</sup> ( $\approx 4.6 \times 10^4 (\Omega \text{ m})^{-1}$ ), resulting in the highest  $PF$  values of  $2.7 \times 10^{-3} \text{ W K}^{-2} \text{ m}^{-1}$  ( $\text{Bi}_2\text{Te}_3$ ) and  $1.4 \times 10^{-3} \text{ W K}^{-2} \text{ m}^{-1}$  ( $\text{Sb}_2\text{Te}_3$ ) (Table 1).  $\sigma$  values of  $\text{Bi}_2\text{Te}_3$  films deposited on glass and 50  $\mu\text{m}$ —thick Kapton<sup>®</sup> substrates are  $1.2 \times 10^4 (\Omega \text{ m})^{-1}$  and  $2.8 \times 10^4 (\Omega \text{ m})^{-1}$ , respectively. For  $\text{Sb}_2\text{Te}_3$  films,  $\sigma$  values of  $3.0 \times 10^4 (\Omega \text{ m})^{-1}$  (for glass) and  $3.2 \times 10^4 (\Omega \text{ m})^{-1}$  (for 25  $\mu\text{m}$  - Kapton<sup>®</sup>) are obtained. The films with highest  $PF$  values revealed a more compact and dense structure (so, more connected grains). Disoriented grains create a higher electrical resistivity due to a more open structure. XRD spectrum of the  $\text{Bi}_2\text{Te}_3$  film with the

highest  $PF$  value (Figure 2a) shows a preferential growth along the (0 0 15) plane of the  $\text{Bi}_2\text{Te}_3$  crystals. Similar XRD patterns of  $\text{Sb}_2\text{Te}_3$  films (Figure 2b) are observed.

A flexible infrared thermopile sensor based on a single p-n junction has been tested as a proof of concept. The 25  $\mu\text{m}$  Kapton® provides flexibility and lightness to the devices, while it offers high upper working temperature (until 350 °C) and low thermal conductivity (0.12  $\text{W m}^{-1} \text{K}^{-1}$ ). A metal structure was constructed to maintain the cold junctions at RT (heat sink) and to allow only the region of the hot junction to receive the radiation (through a hole in the metal structure), as shown in the Figure 3a.

**Table 1.** Comparison of TE properties of the  $\text{Bi}_2\text{Te}_3$  and  $\text{Sb}_2\text{Te}_3$  in the present study with other reported by other authors (with different techniques).

Film	Thickness ( $\mu\text{m}$ )	Substrate	$S$ ( $\mu\text{VK}^{-1}$ )	$\sigma_{\text{RT}}$ ( $\Omega \text{m}^{-1}$ )	$PF$ ( $\times 10^{-3} \text{W K}^{-2} \text{m}^{-1}$ )
$\text{Bi}_2\text{Te}_3/\text{Sb}_2\text{Te}_3$	0.4	glass/polyimide	-224/176	$5.3 \times 10^4/4.6 \times 10^4$	2.7/1.4
$\text{Sb}_2\text{Te}_3$ [3]	-	polyimide	135	$2.8 \times 10^4$	0.5
$\text{Bi}_2\text{Te}_3$ [4]	1.3	polyimide	119	$7.0 \times 10^4$	1 ( $\text{Bi}_2\text{Te}_3$ )
$\text{Sb}_2\text{Te}_3/\text{Bi}_{1.8}\text{Te}_{3.2}$ [5]	70	Glass-textile/polyimide	-138/120	$1.0 \times 10^4/1.0 \times 10^4$	0.3/0.2

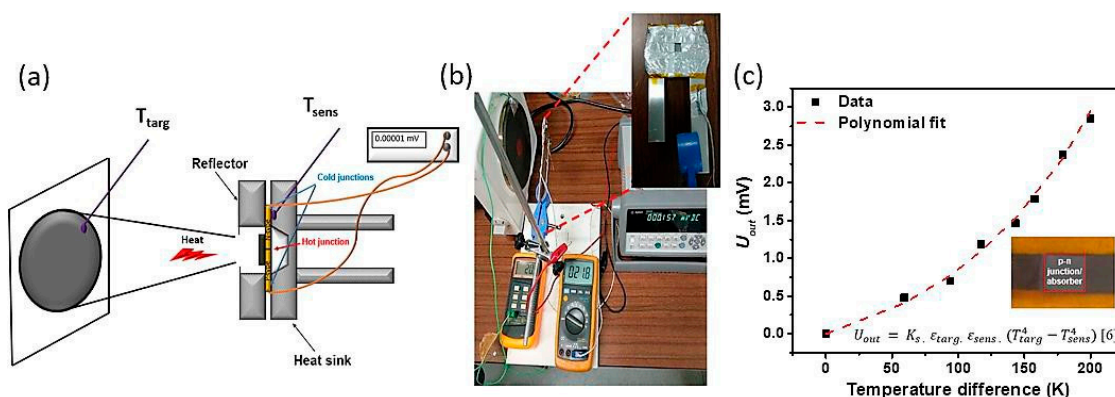


**Figure 2.** XRD patterns for (a)  $\text{Bi}_2\text{Te}_3$  and (b)  $\text{Sb}_2\text{Te}_3$  films deposited on the three substrates. Average NCs size is indicated for each film. The presence of Bi (for  $\text{Bi}_2\text{Te}_3$  films) and Te (for  $\text{Sb}_2\text{Te}_3$  films) diffraction peaks confirms that the films are Bi- and Te-rich.

An example of the thermal test is given in the Figure 3b. Figure 3c shows that the experimental data are fitted with a 4-order polynomial, according to the Equation [6] shown in the inset of Figure 3c.  $K_s$  is the instrument factor of the sensor ( $K_s = 5.50 \times 10^{-14}$ ),  $\epsilon_{\text{targ}}$  is the emissivity of the target disk ( $\epsilon_{\text{targ}} = 0.9$ ),  $T_{\text{targ}}$  is the temperature of the disk and  $T_{\text{sens}}$  is the temperature of the sensor.  $\epsilon_{\text{sens}} = 1$  considering the internal reflections inside the thermopile case, and therefore, the whole structure behaves as a cavity blackbody with high emissivity [6]. The responsivity ( $R_s$ ) is obtained by the slope of the output voltage as a function of absorbed heat radiation power [2], and is 0.19  $\text{V W}^{-1}$  for our sensor. Specific detectivity ( $D^*$ ) can be calculated by [2]

$$D^* = \frac{\sqrt{A_{\text{abs}}} \sqrt{\Delta f}}{NEP} \quad (1)$$

where  $A$  is area of sensor (25  $\text{mm}^2$ ) and  $NEP$  is the noise equivalent power which is the quotient of RMS of the voltage ( $v_n$ ) and  $R_s$  [2]. A  $v_n = 3.9 \text{ nV}$  was obtained taking in account the  $\Delta f = 1 \text{ Hz}$ ,  $T = 298 \text{ K}$  and  $R = 910 \Omega$ .  $NEP$  value was estimated to be 20  $\text{nW}$ . A  $D^*$  value of  $2.50 \times 10^7 \text{ cm} \sqrt{\text{Hz}} \text{W}^{-1}$  was obtained.



**Figure 3.** (a) Scheme of operation of the TE device used as radiation sensor; (b) thermal test (c) output voltage plotted against the temperature difference ( $T_{\text{targ}} - T_{\text{sens}}$ ); inset: photograph of the sensor and equation [6].

#### 4. Conclusions

The developed telluride films have the highest  $PF$  values among the results regarding flexible films with thickness below  $1 \mu\text{m}$ , reported up to now. Their high  $S$  values, together with a flexible structure make them suitable to be applied as flexible thermal sensors, as proven here.

**Author Contributions:** L.M.G. conceived and designed the experiments; E.V. performed the experiments; E.V., J.F., A.L.P., J.G. analyzed the data; M.F.S. and A.M.P. contributed reagents/materials/analysis tools; E.V. wrote the paper and all authors reviewed the paper.

**Acknowledgments:** This work is supported by FCT with the reference project UID/EEA/04436/2013, by FEDER funds through the COMPETE 2020—Programa Operacional Competitividade e Internacionalização (POCI) with the reference project POCI-01-0145-FEDER-006941. EMFV and JF is grateful for financial support through the FCT grants SFRH/BPD/95905/2013 and SFRH/BD/121679/2016.

**Conflicts of Interest:** The authors declare no conflict of interest. The founding sponsors had no role in the design of the study; in the collection, analyses, or interpretation of data; in the writing of the manuscript, and in the decision to publish the results.

#### References

- Mamur, H.; Bhuiyan, M.R.A.; Korkmaz, F.; Nil, M. A review on bismuth telluride ( $\text{Bi}_2\text{Te}_3$ ) nanostructure for thermoelectric applications. *Renew. Sustain. Energy Rev.* **2018**, *82*, 4159–4169. doi:10.1016/j.rser.2017.10.112.
- Xu, D.; Xiong, B.; Wang, Y. Micromachined thermoelectric IR sensors fabricated by a self-aligned process. *Smart. Mater. Struct.* **2011**, *20*, 015013–21. doi:10.1088/0964-1726/20/1/015013.
- Shen, S.; Zhu, W.; Deng, Y.; Zhao, H.; Peng, Y.; Wang, C. Enhancing thermoelectric properties of  $\text{Sb}_2\text{Te}_3$  flexible thin film through microstructure control and crystal preferential orientation engineering. *Appl. Surf. Sci.* **2017**, *414*, 197–204. doi:10.1016/j.apsusc.2017.04.074.
- Nuthongkum, P.; Sakdanuphab, R.; Horprathum, M.; Sakulkalavek, A. [Bi]:[Te] Control, Structural and Thermoelectric Properties of Flexible  $\text{Bi}_x\text{Te}_y$  Thin Films Prepared by RF Magnetron Sputtering at Different Sputtering Pressures. *J. Electron. Mater.* **2017**, *46*, 6444–6450. doi:10.1007/s11664-017-5671-x.
- Cao, Z.; Tudor, M.J.; Torah, R.N.; Beeby, S.P. Screen Printable Flexible  $\text{BiTe-SbTe}$ -Based Composite Thermoelectric Materials on Textiles for Wearable Applications. *IEEE Trans. Electron. Devices* **2016**, *63*, 4024–4030. doi:10.1109/TED.2016.2603071.
- Sebastián, E.; Armien, C.; Gómez-Elvira, J. Infrared temperature measurement uncertainty for unchopped thermopile in presence of case thermal gradients. *Infrared Phys. Technol.* **2011**, *54*, 75–83. doi:10.1016/j.infrared.2010.12.038.

